



Material Content Data Sheet



Sales Product Name		SAK-XC164CM-8F40F AA		Issued		19. January 2018		
MA#		MA001119570						
Package		PG-LQFP-64-14		Weight*		375.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	19.437	5.18	5.18	51756	51756
leadframe	non noble metal	magnesium	7439-95-4	0.172	0.05		457	
	inorganic material	silicon	7440-21-3	0.743	0.20		1979	
	non noble metal	nickel	7440-02-0	3.431	0.91		9135	
	non noble metal	copper	7440-50-8	110.016	29.29	30.45	292938	304509
wire	noble metal	gold	7440-57-5	1.196	0.32	0.32	3184	3184
encapsulation	organic material	carbon black	1333-86-4	1.153	0.31		3070	
	plastics	epoxy resin	-	31.132	8.29		82894	
	inorganic material	silicondioxide	60676-86-0	198.321	52.80	61.40	528070	614034
leadfinish	non noble metal	tin	7440-31-5	4.118	1.10	1.10	10964	10964
plating	noble metal	silver	7440-22-4	1.663	0.44	0.44	4428	4428
glue	plastics	epoxy resin	-	0.836	0.22		2225	
	noble metal	silver	7440-22-4	3.343	0.89	1.11	8900	11125
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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